Lincoln 2 D2_P2_08131

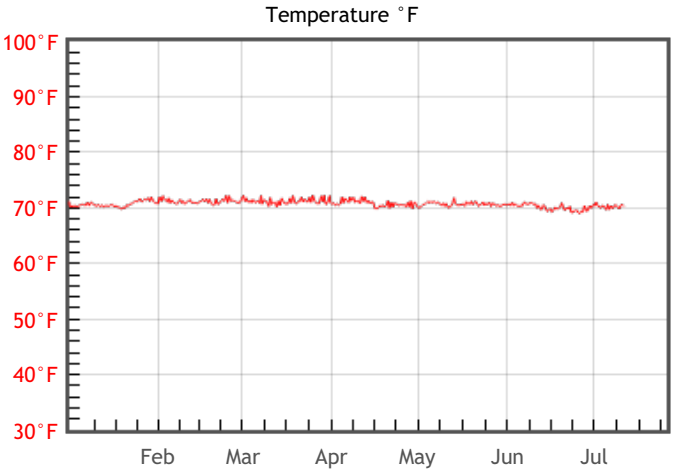
Main Library • Illinois History and Lincoln Collections • Seventh Deck • Range D2
UIUC Library PresCons

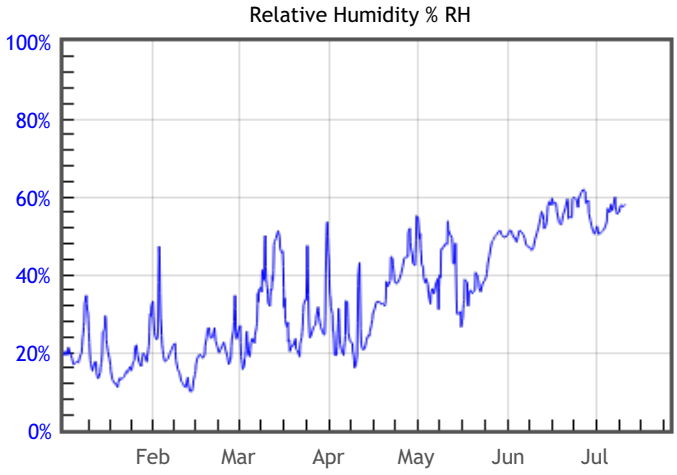
2016-01-01 to 2016-07-11
6 months, 11 days

Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	OK TWPI = 57	Generally OK, but fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics will be at elevated risk due to the cumulative effects of temperature and humidity
Mechanical Damage Physical damage to hygroscopic materials	RISK % DC = 1.71 % EMC min = 4.1 % EMC max = 10.2	Heightened risk of physical damage to any hygroscopic material, such as paintings, rare books, furniture, paper, leather, film, or color photos, due to extremely low or high levels of humidity, and / or excessive humidity fluctuation.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 10.2	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

Graphs





Statistics

Temperature		Relative Humidity		Dew Point	
T°F Mean	70.7	**%RH Mean**	34	**DP°F Mean**	38.8
T°F Median	70.7	**%RH Median**	33	**DP°F Median**	39.8
T°F Stdev	0.8	**%RH Stdev**	15	**DP°F Stdev**	11.7
T°F Min	68.7	**%RH Min**	9	**DP°F Min**	9.1
T°F Max	74.1	**%RH Max**	63	**DP°F Max**	56.8

Lincoln 7 E16_P2_06268

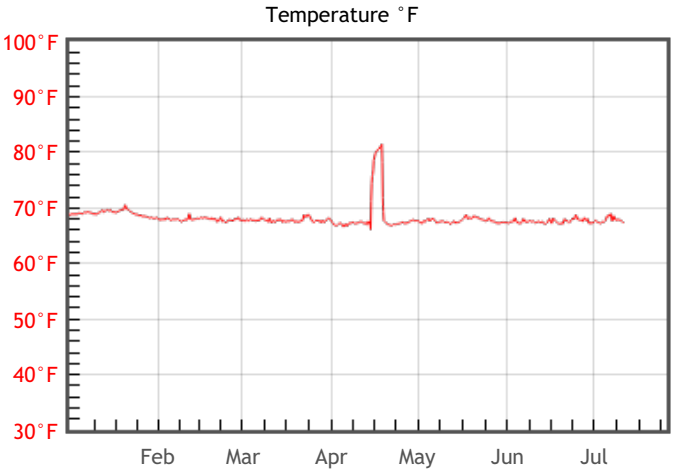
Main Library • Illinois History and Lincoln Collections • Seventh Deck • Range E16
UIUC Library PresCons

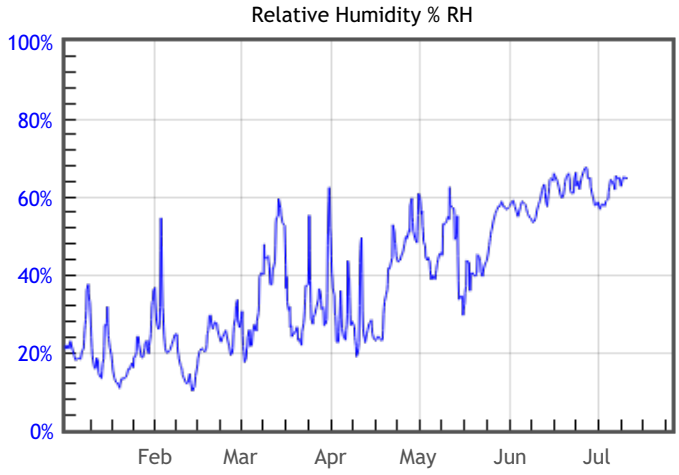
2016-01-01 to 2016-07-11
6 months, 11 days

Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	OK TWPI = 60	Generally OK, but fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics will be at elevated risk due to the cumulative effects of temperature and humidity
Mechanical Damage Physical damage to hygroscopic materials	RISK % DC = 1.98 % EMC min = 4.5 % EMC max = 11.6	Heightened risk of physical damage to any hygroscopic material, such as paintings, rare books, furniture, paper, leather, film, or color photos, due to extremely low or high levels of humidity, and / or excessive humidity fluctuation.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	RISK % EMC max = 11.6	Heightened risk of metal corrosion due to extended periods of high levels of humidity.

Graphs





Statistics

Temperature		Relative Humidity		Dew Point	
T°F Mean	68.1	**%RH Mean**	38	**DP°F Mean**	39.3
T°F Median	67.8	**%RH Median**	36	**DP°F Median**	40.3
T°F Stdev	1.8	**%RH Stdev**	17	**DP°F Stdev**	12
T°F Min	64.2	**%RH Min**	10	**DP°F Min**	9
T°F Max	82.2	**%RH Max**	69	**DP°F Max**	57.4

Lincoln 8 E4_P2_03108

Main Library • Illinois History and Lincoln Collections • Eighth Deck • Range E4
UIUC Library PresCons

to
NaN years, NaN months, NaN days

No data found for given time frame.

Lincoln 8 E4_P2_03108_b

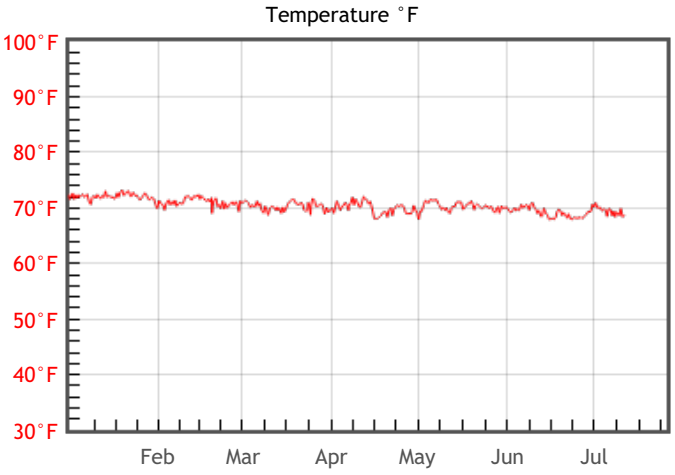
Main Library • Illinois History and Lincoln Collections • Eighth Deck • Range E4
UIUC Library PresCons

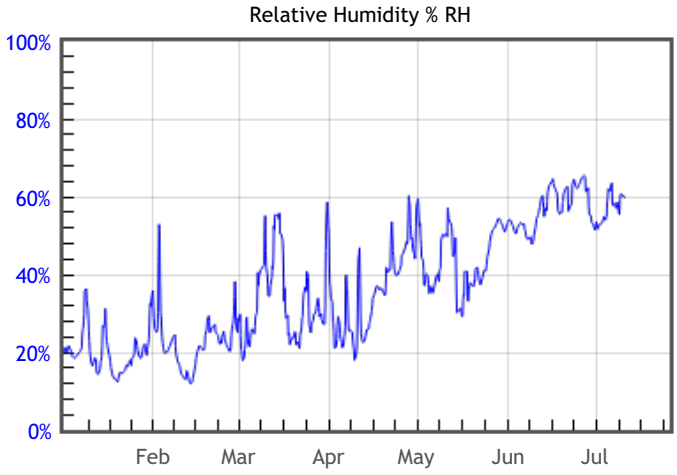
2016-01-01 to 2016-07-11
6 months, 11 days

Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	OK TWPI = 55	Generally OK, but fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics will be at elevated risk due to the cumulative effects of temperature and humidity
Mechanical Damage Physical damage to hygroscopic materials	RISK % DC = 1.76 % EMC min = 4.5 % EMC max = 10.8	Heightened risk of physical damage to any hygroscopic material, such as paintings, rare books, furniture, paper, leather, film, or color photos, due to extremely low or high levels of humidity, and / or excessive humidity fluctuation.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	RISK % EMC max = 10.8	Heightened risk of metal corrosion due to extended periods of high levels of humidity.

Graphs





Statistics

Temperature		Relative Humidity		Dew Point	
T°F Mean	70.4	**%RH Mean**	37	**DP°F Mean**	40.4
T°F Median	70.1	**%RH Median**	35	**DP°F Median**	41
T°F Stdev	1.8	**%RH Stdev**	15	**DP°F Stdev**	10.8
T°F Min	66.3	**%RH Min**	11	**DP°F Min**	15
T°F Max	78.6	**%RH Max**	67	**DP°F Max**	57.5

lincolncoll TEMPwall_1244897

Main Library • Illinois History and Lincoln Collections • Third • Reading Room
UIUC Library PresCons

to
NaN years, NaN months, NaN days

No data found for given time frame.

eClimateNotebook® - Image Permanence Institute - Rochester Institute of Technology - © 2016
Overview Report - Created: 2016-07-25

lincolncoll TEMPyoke_1244889

Main Library • Illinois History and Lincoln Collections • Third • Reading Room
UIUC Library PresCons

to
NaN years, NaN months, NaN days

No data found for given time frame.

P2_02622

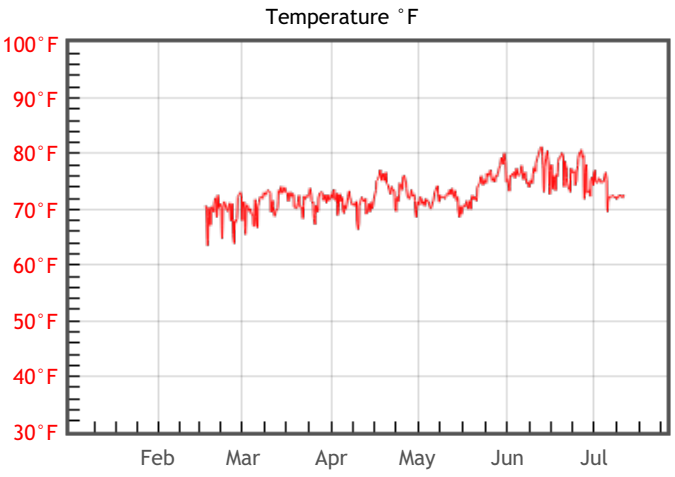
Main Library • Illinois History and Lincoln Collections • Third • Temp
UIUC Library PresCons

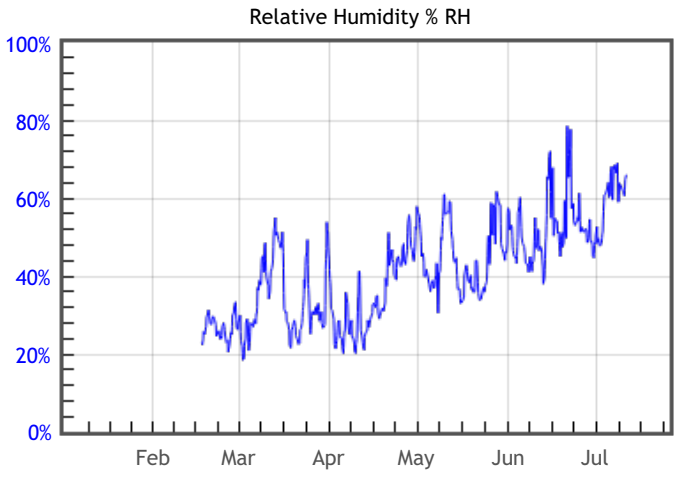
2016-02-17 to 2016-07-11
4 months, 24 days

Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	RISK TWPI = 40	Accelerated rate of chemical decay in all organic materials due to the cumulative effects of temperature and humidity, with especially high risk for fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics.
Mechanical Damage Physical damage to hygroscopic materials	OK % DC = 1.19 % EMC min = 6 % EMC max = 10.2	Generally OK, but sensitive or fast responding hygroscopic materials such as paintings, rare books, vellum manuscripts or musical instruments will be at elevated risk of physical damage due to fluctuations of humidity.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0.06	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 10.2	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

Graphs





Statistics

Temperature		Relative Humidity		Dew Point	
T°F Mean	73	**%RH Mean**	41	**DP°F Mean**	47.1
T°F Median	72.6	**%RH Median**	42	**DP°F Median**	48.3
T°F Stdev	3.1	**%RH Stdev**	13	**DP°F Stdev**	10.2
T°F Min	63.1	**%RH Min**	16	**DP°F Min**	22.6
T°F Max	81.8	**%RH Max**	83	**DP°F Max**	71.7

Temp IHLC_P2_03110

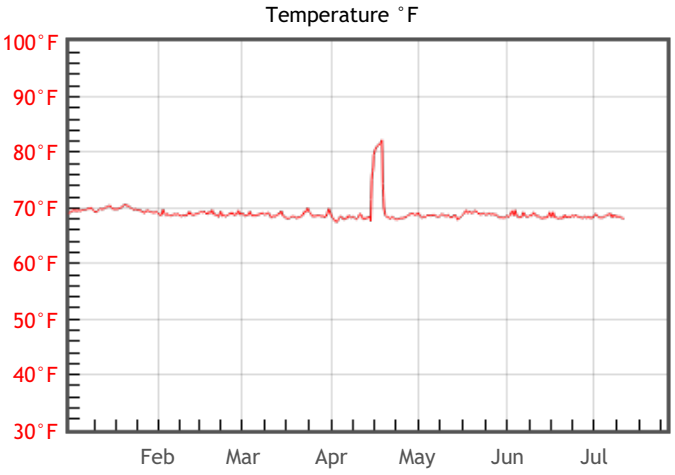
Main Library • Illinois History and Lincoln Collections • Seventh Deck • Temp
UIUC Library PresCons

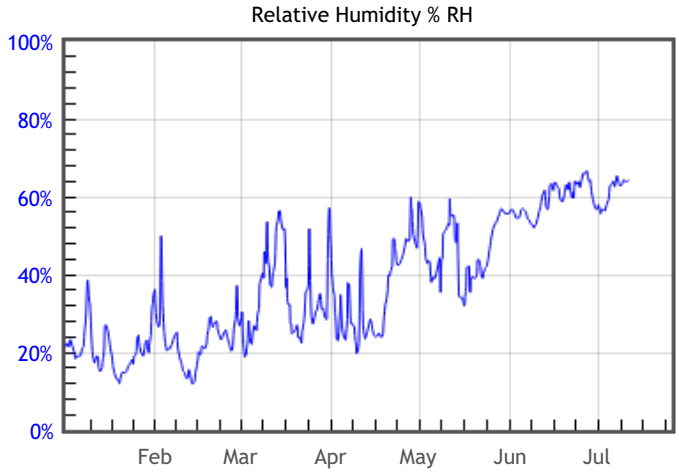
2016-01-01 to 2016-07-11
6 months, 11 days

Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	OK TWPI = 59	Generally OK, but fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics will be at elevated risk due to the cumulative effects of temperature and humidity
Mechanical Damage Physical damage to hygroscopic materials	RISK % DC = 1.92 % EMC min = 4.5 % EMC max = 11.4	Heightened risk of physical damage to any hygroscopic material, such as paintings, rare books, furniture, paper, leather, film, or color photos, due to extremely low or high levels of humidity, and / or excessive humidity fluctuation.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	RISK % EMC max = 11.4	Heightened risk of metal corrosion due to extended periods of high levels of humidity.

Graphs





Statistics

Temperature		Relative Humidity		Dew Point	
T°F Mean	69	**%RH Mean**	38	**DP°F Mean**	40
T°F Median	68.7	**%RH Median**	36	**DP°F Median**	41.2
T°F Stdev	1.7	**%RH Stdev**	16	**DP°F Stdev**	11.4
T°F Min	66.9	**%RH Min**	12	**DP°F Min**	13.8
T°F Max	83.1	**%RH Max**	68	**DP°F Max**	57.5